FT_TGF_030_AB_63

Thermal Pad

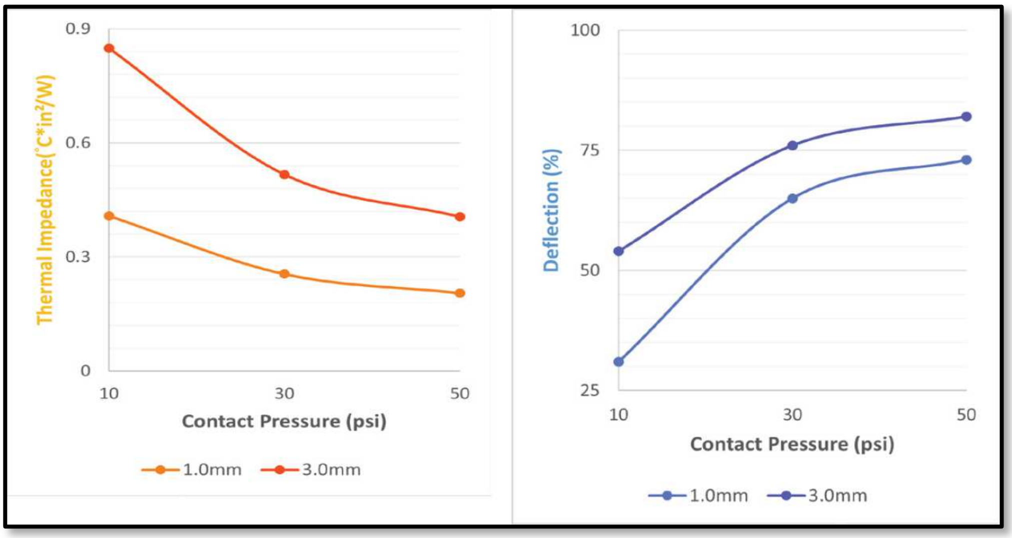
Our thermal foams also called Gap Pads or Gap Filler are silicone-based heat-conducting materials that solve heat dissipation problems. The TGF-030-AB is a mattress specifically designed for applications requiring medium cooling. Indeed, it is an excellent thermal conductor of 3.0W/mK, with good thermal resistance thus facilitating heat transfer and also has excellent electrical insulation. Below 1mm, the mattress is difficult to use in pick-in-place for robotic production, in this case it will be necessary to adjust its hardness before use. We can cut according to customer's plan.

Application areas: Electronic components - Electric vehicles, 5G, Automatic driving system, Mobile phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, Motherboard, Power supply, Heat sink, LCD-TV, laptop, PC, telecom device, wireless hub, DDR ll module, etc.

Technical characteristics

Features	TGF-030-AB	Unit	Tolerance	Test Method
Color	Purple	-	-	Colorimètre CIE 1976
Density	2.8	g/cm^3	+/- 10%	ASTM D792
Thickness	1 - 8	mm	-	ASTM D374
Hardness	20	shore 00	+/- 10	ASTM D2240
Sizes	310*310	mm	-	-
Thermal conductivity	3	W/mK	+/- 10%	ASTM D5470 Modified
Weight loss	< 1	%	-	ASTM E595 Modified
Elongation	> 150	%	-	ASTM D412
Breakdown voltage	≥ 5	kV/mm	-	ASTM D149
Volume resistance	10^{11}	Ohm-m	-	ASTM D257
UL certification	V-0	-	-	UL 94
Temperature	-50 to 150	°C	-	-

The TGF_030_AB is available in thicknesses of 1 to 8 mm.



The results were obtained under laboratory conditions and should be considered only as an indication. As AB2E has no control over its customers' equipment and many other factors, it is the user's responsibility to carry out its own tests to ensure that the product corresponds to its needs.